

The documentation and process conversion measures necessary to comply with this revision shall be completed by 5 February 2003.

INCH-POUND

MIL-PRF-19500/562D
5 November 2003
SUPERSEDING
MIL-PRF-19500/562C
30 July 1999

PERFORMANCE SPECIFICATION

SEMICONDUCTOR DEVICE, FIELD EFFECT TRANSISTOR, P-CHANNEL, SILICON,
TYPES 2N6804 AND 2N6806
JAN, JANTX, JANTXV, JANS, JANHC, AND JANKC

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the performance requirements for a P-channel, enhancement-mode, MOSFET, power transistor intended for use in high density power switching applications. Four levels of product assurance are provided for each encapsulated device type as specified in MIL-PRF-19500 and two levels of product assurance are provided for each unencapsulated device type.

1.2 Physical dimensions. See figure 1, TO-204AA (formerly TO-3), figures 2, and 3 for JANHC and JANKC die dimensions.

* 1.3 Maximum ratings. Unless otherwise specified, $T_A = +25^\circ\text{C}$.

Type	P_T (1) $T_C = +25^\circ\text{C}$	P_T $T_A = +25^\circ\text{C}$	V_{DS}	V_{DG}	V_{GS}	I_{D1} (2) (3) $T_C = +25^\circ\text{C}$	I_{D2} (2) $T_C = +100^\circ\text{C}$	I_S	I_{DM} (4)	T_J and T_{STG}
	<u>W</u>	<u>W</u>	<u>V dc</u>	<u>V dc</u>	<u>V dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A(pk)</u>	<u>°C</u>
2N6804	75	4	-100	-100	± 20	-11.0	-7.0	-11.0	-50	-55 to +150
2N6806	75	4	-200	-200	± 20	-6.5	-4.0	-6.5	-28	-55 to +150

(1) Derate linearly 0.6 W/°C for $T_C > +25^\circ\text{C}$.

(2) The following formula derives the maximum theoretical I_D limit. I_D is also limited by package and internal wires and may be limited by pin diameter:

$$I_D = \sqrt{\frac{T_{JM} - T_C}{(R_{\theta JC}) \times (R_{DS(on)} \text{ at } T_{JM})}}$$

(3) See figure 4, maximum drain current graph.

(4) $I_{DM} = 4 \times I_{D1}$ as calculated in note 2.

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Defense Supply Center, Columbus, ATTN: DSCC-VAC, Post Office Box 3990, Columbus, OH 43216-5000, by using the Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

1.4 Primary electrical characteristics at $T_C = +25^\circ\text{C}$.

Type	Min $V_{(BR)DSS}$ $V_{GS} = 0\text{ V}$ $I_D = -1.0\text{ mA dc}$	$V_{GS(th)1}$ $V_{DS} \geq V_{GS}$ $I_D = -0.25\text{ mA dc}$	Max I_{DSS1} $V_{GS} = 0\text{ V}$	Max $r_{DS(on)} (1)$ $V_{GS} = -10\text{ V dc}$		$R_{\theta JC}$ maximum	
			$V_{DS} = 80$ percent of rated V_{DS}	$T_J = +25^{\circ}\text{C}$ at I_{D2}	$T_J = +150^{\circ}\text{C}$ at I_{D2}		
	<u>V dc</u>	<u>V dc</u>		<u>μA dc</u>	<u>ohm</u>	<u>ohm</u>	<u>°C/W</u>
		<u>Min</u>	<u>Max</u>				
2N6804	-100	-2.0	-4.0	-25	0.30	0.60	1.67
2N6806	-200	-2.0	-4.0	-25	0.80	1.80	1.67

(1) Pulsed (see 4.5.1).

2. APPLICABLE DOCUMENTS

2.1 General. The documents listed in this section are specified in sections 3 and 4 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements documents cited in sections 3 and 4 of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DODISS) and supplement thereto, cited in the solicitation (see 6.2).

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-19500 - Semiconductor Devices, General Specification for.

STANDARD

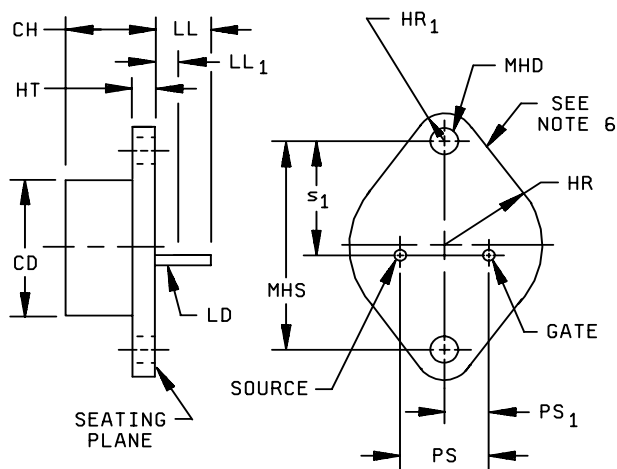
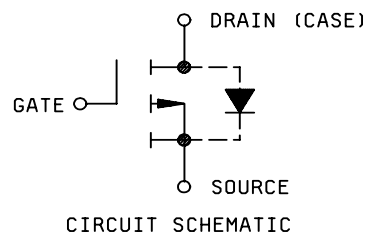
DEPARTMENT OF DEFENSE

MIL-STD-750 - Test Methods for Semiconductor Devices.

(Unless otherwise indicated, copies of the above specifications, standards, and handbooks are available from the Document Automation and Production Services (DAPS), Building 4D (DPM-DODSSP), 700 Robbins Avenue, Philadelphia, PA 19111-5094.)

* 2.3 Order of precedence. In the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

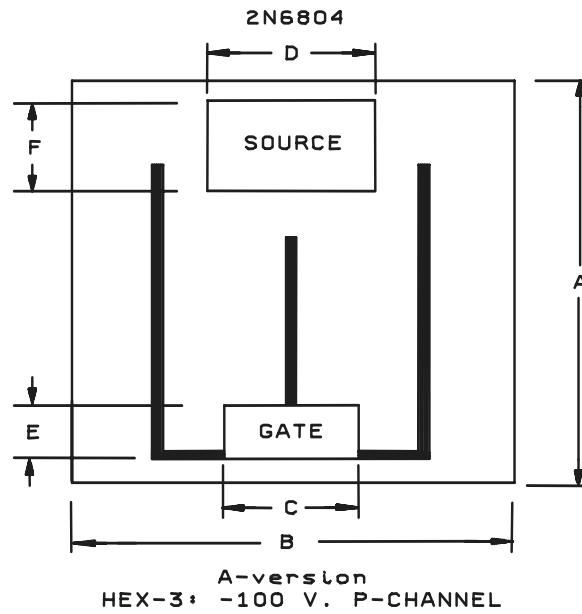
Symbol	Dimensions				Notes
	Inches		Millimeters		
	Min	Max	Min	Max	
CH	.250	.360	6.35	9.15	3
LD	.038	.043	0.97	0.110	
CD		.875		22.23	
PS	.420	.440	10.67	11.18	3
PS ₁	.205	.225	5.21	5.72	3
HT	.060	.135	1.52	3.43	
LL	.312	.500	7.92	12.70	
LL ₁		.050		1.27	
MHD	.151	.161	3.84	4.09	
MHS	1.177	1.197	29.90	30.40	
HR	.495	.525	12.57	13.34	
HR ₁	.131	.188	3.33	4.78	
s ₁	.655	.675	16.64	17.15	



NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. These dimensions should be measured at points .050 inch (1.27 mm) to .055 inch (1.40 mm) below seating plane. Measurement will be made at the seating plane.
4. The seating plane of the header shall be flat within .001 inch (0.03 mm) concave to .004 inch (0.10 mm) convex inside a .930 inch (23.62 mm) diameter circle on the center of the header and flat within .001 inch (0.03 mm) concave to .006 inch (0.15 mm) convex overall.
5. Mounting holes shall be deburred on the seating plane side.
6. Drain is electrically connected to case.
7. In accordance with ASME Y14.5M, diameters are equivalent to ϕ x symbology.

* FIGURE 1. Physical dimensions of transistor (TO-204AA).

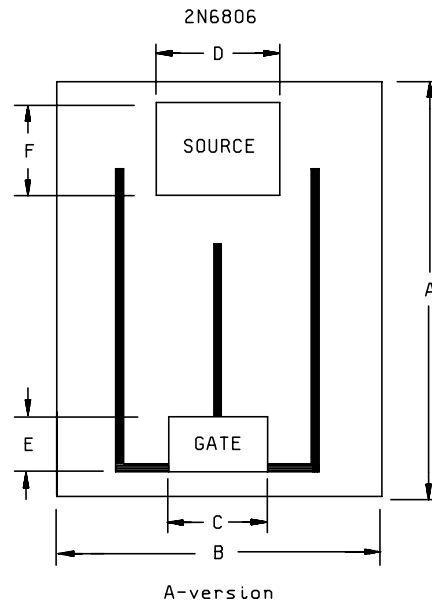


Ltr	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	.172	.186	4.37	4.72
B	.106	.120	2.69	3.05
C	.021	.029	0.53	0.74
D	.035	.043	0.89	1.09
E	.014	.022	0.36	0.56
F	.025	.036	0.64	0.91

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. The physical characteristics of the die are:
Back metals are chromium, nickel, and silver.
Top metal is aluminum
Back contact is the drain.
4. The die thickness is 0.0187 inch (0.474 mm), the tolerance is ± 0.0050 inch (0.13 mm).
5. Unless otherwise specified, tolerance is ± 0.0005 inch (0.13 mm).

FIGURE 2. JANHCA and JANKCA die dimensions for 2N6804.



Ltr	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	.173	.187	4.39	4.75
B	.108	.124	2.74	3.15
C	.022	.030	0.56	0.76
D	.030	.038	0.76	0.97
E	.012	.020	0.30	0.51
F	.021	.029	0.53	0.74

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. The physical characteristics of the die are:
Back metals are chromium, nickel, and silver.
Top metal is aluminum
Back contact is the drain.
4. The die thickness is .0187 inch (0.474 mm), the tolerance is $\pm .0050$ inch (0.13 mm).
5. Unless otherwise specified, tolerance is $\pm .0005$ inch (0.13 mm).

FIGURE 3. JANHCA and JANKCA die dimensions for 2N6806.

3. REQUIREMENTS

* 3.1 General. The individual item requirements shall be as specified in MIL-PRF-19500 and as modified herein.

* 3.2 Qualification. Devices furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturer's list (QML) before contract award (see 4.2 and 6.3).

* 3.3 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in MIL-PRF-19500 and as follows.

nC ----- nano Coulomb.

* 3.4 Interface and physical dimensions. The interface and physical dimensions shall be as specified in MIL-PRF-19500 and on figure 1 (TO-204AA), 2, and 3 (JANHC and JANKC) herein.

3.4.1 Lead finish. Lead finish shall be solderable in accordance with MIL-PRF-19500, MIL-STD-750 and herein. Where a choice of lead finish is desired, it shall be specified in the acquisition document (see 6.2).

3.4.2 Internal construction. Multiple chip construction shall not be permitted.

3.5 Marking. Devices shall be marked in accordance with MIL-PRF-19500.

3.6 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in 1.3, 1.4, and table I herein.

3.7 Electrostatic discharge protection. The devices covered by this specification require electrostatic protection.

3.7.1 Handling. MOS devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. The following handling practices shall be followed:

- a. Devices shall be handled on benches with conductive handling devices.
- b. Ground test equipment, tools, and personnel handling devices.
- c. Do not handle devices by the leads.
- d. Store devices in conductive foam or carriers.
- e. Avoid use of plastic, rubber, or silk in MOS areas.
- f. Maintain relative humidity above 50 percent if practical.
- g. Care shall be exercised, during test and troubleshooting, to apply not more than maximum rated voltage to any lead.
- h. Gate must be terminated to source, $R \leq 100 \text{ k}\Omega$, whenever bias voltage is to be applied drain to source.

3.8 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table I.

* 3.9 Workmanship. Semiconductor devices shall be processed in such a manner as to be uniform in quality and shall be free from other defects that will affect life, serviceability, or appearance.

4. VERIFICATION

4.1 Classification of inspections. The inspection requirements specified herein are classified as follows:

- a. Qualification inspection (see 4.2).
- b. Screening (see 4.3).
- c. Conformance inspection (see 4.4 and tables I and II).

4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-19500 and table II herein. Alternate flow is allowed for qualification inspection in accordance with MIL-PRF-19500.

* 4.2.1 Group E qualification. Group E inspection shall be performed for qualification or re-qualification only. In case qualification was awarded to a prior revision of the associated specification that did not request the performance of table II tests, the tests specified in table II herein shall be performed by the first inspection lot of this revision to maintain qualification.

* 4.2.2 JANHC and JANKC die. Qualification shall be in accordance with MIL-PRF-19500.

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* 4.3 Screening (JANS, JANTX, and JANTXV levels only). Screening shall be in accordance with table IV of MIL-PRF-19500 and as specified herein. The following measurements shall be made in accordance with table I herein. Devices that exceed the limits of table I herein shall not be acceptable.

Screen (see table IV of MIL-PRF-19500) (1) (2)	Measurement	
	JANS level	JANTX and JANTXV levels
(3)	Gate stress test (see 4.3.2)	Gate stress test (see 4.3.2)
(3) (4)	Method 3470 of MIL-STD-750, (optional) (see 4.3.4)	Method 3470 of MIL-STD-750, (optional) (see 4.3.4)
(3) 3c	Method 3161 of MIL-STD-750, (see 4.3.3)	Method 3161 of MIL-STD-750, (see 4.3.3)
9	I_{GSSF1} , I_{GSSR1} , I_{DSS1} , Subgroup 2 of table I herein.	Subgroup 2 of table I herein.
10	Method 1042 of MIL-STD-750, test condition B	Method 1042 of MIL-STD-750, test condition B
11	I_{GSSF1} , I_{GSSR1} , I_{DSS1} , $r_{DS(on)1}$, $V_{GS(th)1}$, subgroup 2 of table I herein; $\Delta I_{GSSF1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{GSSR1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{DSS1} = \pm 25$ μ A dc or ± 100 percent of initial value, whichever is greater.	I_{GSSF1} , I_{GSSR1} , I_{DSS1} , $r_{DS(on)1}$, $V_{GS(th)1}$, subgroup 2 of table I herein;
12	Method 1042 of MIL-STD-750, test condition A, $t = 240$ hours	Method 1042 of MIL-STD-750, test condition A; $T_A = +175^{\circ}\text{C}$ and $t = 48$ hours
13	Subgroups 2 and 3 of table I herein; $\Delta I_{GSSF1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{GSSR1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{DSS1} = \pm 25$ μ A dc or ± 100 percent of initial value, whichever is greater. $\Delta r_{DS(on)1} = \pm 20$ percent of initial value. $\Delta V_{GS(th)1} = \pm 20$ percent of initial value.	Subgroups 2 of table I herein; $\Delta I_{GSSF1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{GSSR1} = \pm 20$ nA dc or ± 100 percent of initial value, whichever is greater. $\Delta I_{DSS1} = \pm 25$ μ A dc or ± 100 percent of initial value, whichever is greater. $\Delta r_{DS(on)1} = \pm 20$ percent of initial value. $\Delta V_{GS(th)1} = \pm 20$ percent of initial value.

- (1) At the end of the test program, I_{GSSF1} , I_{GSSR1} , and I_{DSS1} are measured.
- (2) An out-of-family program to characterize I_{GSSF1} , I_{GSSR1} , I_{DSS1} and $V_{GS(th)1}$ shall be invoked.
- (3) Shall be performed anytime before screen 9.
- (4) Method 3470 is optional if performed as a sample in group A, subgroup 5.

* 4.3.1 Screening (JANHC and JANKC). Screening of die shall be in accordance with MIL-PRF-19500. As a minimum, die shall be 100-percent probed in accordance with table I, subgroup 2.

* 4.3.2 Gate stress test. Apply $V_{GS} = \pm 30$ V minimum for $t = 250$ μ s minimum.

* 4.3.3 Thermal impedance ($Z_{\theta JC}$ measurements). The $Z_{\theta JC}$ measurements shall be performed in accordance with method 3161 of MIL-STD-750. The maximum limit (not to exceed figure 5, thermal impedance curves and the table I, subgroup 2 limits) for $Z_{\theta JC}$ in screening (table IV of MIL-PRF-19500) shall be derived by each vendor by means of statistical process control. When the process has exhibited control and capability, the capability data shall be used to establish the fixed screening limit. In addition to screening, once a fixed limit has been established, monitor all future sealing lots using a random five piece sample from each lot to be plotted on the applicable X bar R chart. If a lot exhibits an out of control condition, the entire lot shall be removed from the line and held for engineering evaluation and disposition. This procedure may be used in lieu of an inline process monitor.

- a. Measuring current (I_M) 10 mA.
- b. Drain heating current (I_H) 4 A minimum.
- c. Heating time (t_H) 100 ms.
- d. Drain-source heating voltage (V_H) 25 V minimum.
- e. Measurement time delay (t_{MD}) 30 to 60 μ s.
- f. t_{SW} sample window time 10 μ s (maximum).

* 4.3.4 Unclamped inductive switching.

- a. Peak current (I_D) Rated I_{D1} .
- b. Peak gate voltage (V_{GS}) -10 V.
- c. Gate to source resistor (R_{GS}) $25 \Omega \leq R_{GS} \leq 200 \Omega$.
- d. Initial case temperature (T_C) $+25^\circ\text{C}$ $+10^\circ\text{C}$, -5°C .
- e. Inductance (L) 100 μ H ± 10 percent.
- f. Number of pulses to be applied 1 pulse minimum.
- g. Pulse repetition rate None.

4.4 Conformance inspection. Conformance inspection shall be in accordance with MIL-PRF-19500. Alternate flow is allowed for quality conformance inspection in accordance with MIL-PRF-19500.

4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with MIL-PRF-19500 and table I herein. Electrical measurements (end-points) shall be in accordance with subgroup 2 of table I herein

4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the conditions specified for subgroup testing in table VIa (JANS) and table VIb (JAN, JANTX, and JANTXV) of MIL-PRF-19500 and herein. Electrical measurements (end-points) shall be in accordance with subgroup 2 of table I herein.

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* 4.4.2.1 Group B inspection table VIa (JANS) of MIL-PRF-19500.

<u>Subgroup</u>	<u>Method</u>	<u>Conditions</u>
B3	1051	Test condition G.
B4	1042	Test condition D; 2,000 cycles. The heating cycle shall be 1 minute minimum.
B5	1042	Accelerated steady-state operation life; test condition A; $V_{DS} = \text{rated}$ $T_A = +175^\circ\text{C}$, $t = 120$ hours. Read and record $V_{(BR)DSS}$ (pre and post) at $1 \text{ mA} = I_D$. Read and record I_{DSS} (pre and post) in accordance with table I, subgroup 2 herein. Deltas for $V_{(BR)DSS}$ shall not exceed 10 percent and I_{DSS} shall not exceed $25 \mu\text{A}$. Accelerated steady-state gate stress; condition B, $V_{GS} = \text{rated}$, $T_A = +175^\circ\text{C}$, $t = 24$ hours.
B5	2037	Bond strength; test condition A.
B6	3161	See 4.5.2.

* 4.4.2.2 Group B inspection, table VIb (JAN, JANTX and JANTXV) of MIL-PRF-19500.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
B2	1051	Test condition G.
B3	1042	Test condition D, 2,000 cycles. The heating cycle shall be 1 minute minimum.
B3	2037	Test condition A. All internal bond wires for each device shall be pulled separately.

* 4.4.3 Group C inspection. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table VII of MIL-PRF-19500 and as follows. Electrical measurements (end-points) shall be in accordance with subgroup 2 of table I herein.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
C2	2036	Test condition A; weight = 10 pounds; $t = 15 \text{ s}$.
C5	3161	See 4.5.2.
C6	1042	Test condition D, 6,000 cycles. The heating cycle shall be 1 minute minimum.

* 4.4.4 Group E inspection. Group E inspection shall be conducted in accordance with the conditions specified for subgroup testing in table IX of MIL-PRF-19500 and as specified in table II herein. Electrical measurements (end-points) shall be in accordance with table I, subgroup 2 herein.

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables and as follows.

4.5.1 Pulse measurements. Conditions for pulse measurement shall be as specified in section 4 of MIL-STD-750.

4.5.2 Thermal resistance. Thermal resistance measurements shall be performed in accordance with method 3161 of MIL-STD-750. $R_{\theta JC(max)} = 1.67^{\circ}\text{C/W}$.

- a. Measuring current (I_M) 10 mA.
- b. Drain heating current (I_H) 4 A.
- c. Heating time (t_H) Steady-state (see method 3161 of MIL-STD-750 for definition).
- d. Drain-source heating voltage (V_H) 25 V.
- e. Measurement time delay (t_{MD}) 10 to 60 μs .
- f. Sample window time (t_{SW}) 10 μs maximum.

* TABLE I. Group A inspection.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 1</u>						
Visual and mechanical inspection	2071					
<u>Subgroup 2</u>						
Thermal impedance <u>2/</u>	3161	See 4.3.3	$Z_{\theta JC}$		1.2	°C/W
Breakdown voltage, drain to source	3407	Bias condition C, $V_{GS} = 0$ V; $I_D = -1.0$ mA dc	$V_{(BR)DSS}$	-100 -200		V dc
2N6804 2N6806						
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$; $I_D = -0.25$ mA dc	$V_{GS(th)1}$	-2.0	-4.0	V dc
Gate reverse current	3411	Bias condition C; $V_{DS} = 0$ V; $V_{GS} = +20$ and -20 V dc	I_{GSS1}		±100	nA dc
Drain current	3413	$V_{GS} = 0$; bias condition C; $V_{DS} = 0$ V; $V_{DS} = 80$ percent of rated V_{DS}	I_{DSS1}		-25	μA dc
Static drain to source on-state resistance	3421	$V_{GS} = -10$ V dc; condition A, pulsed (see 4.5.1)	$r_{DS(on)1}$			Ω
2N6804 2N6806		$I_D = -7$ A dc $I_D = -4$ A dc			0.30 0.80	
Drain to source on-state resistance	3421	$V_{GS} = -10$ V dc; condition A, pulsed (see 4.5.1)	$r_{DS(on)2}$			Ω
2N6804 2N6806		$I_D = -11$ A dc $I_D = -6.5$ A dc			0.36 0.94	
Forward voltage (source drain diode)	4011	Pulsed (see 4.5.1), $V_{GS} = 0$ V	V_{SD}			
		For devices with a multiple diode structure				
2N6804 2N6806		$I_S = -11$ A dc $I_S = -6.5$ A dc			-4.7 -6.0	V V

See footnote at end of table.

TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 3</u>						
High temperature operation:		T _C = T _J = +125°C				
Gate reverse current	3411	Bias condition C, V _{DS} = 0 V, V _{GS} = +20 V dc and -20 V dc	I _{GSS2}		± 200	nA dc
Drain current	3413	Bias condition C, V _{GS} = 0 V, V _{DS} = 80 percent rated V _{DS}	I _{DSS2}		-0.25	mA dc
Gate to source voltage (threshold)	3403	V _{DS} ≥ V _{GS} ; I _D = -0.25 mA	V _{GS(th)2}	-1.0		V dc
Static drain to source on-state resistance	3421	V _{GS} = -10 V dc, pulsed (see 4.5.1)	r _{DS(on)3}			Ω
2N6804 2N6806		I _D = -7 A dc I _D = -4 A dc			0.55 1.60	
Low temperature operation:		T _C = T _J = -55°C				
Gate to source voltage (threshold)	3403	V _{DS} ≥ V _{GS} ; I _D = -0.25 mA	V _{GS(th)3}		-5.0	V dc
<u>Subgroup 4</u>						
Switching time test	3472	I _D = rated I _{D2} (see 1.3); V _{GS} = -10 V dc; R _g = 7.5 ohms				
Turn-on delay time			t _{d(on)}			ns
2N6804 2N6806		V _{DD} = -35 V dc V _{DD} = -63 V dc			60 50	
Rise time			t _r			ns
2N6804 2N6806		V _{DD} = -35 V dc V _{DD} = -63 V dc			140 100	

See footnote at end of table.

TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 4</u> – Continued						
Turn-off delay time			$t_{d(off)}$			ns
2N6804		$V_{DD} = -35 \text{ V dc}$			140	
2N6806		$V_{DD} = -63 \text{ V dc}$			100	
Fall time			t_f			ns
2N6804		$V_{DD} = -35 \text{ V dc}$			140	
2N6806		$V_{DD} = -63 \text{ V dc}$			80	
<u>Subgroup 5</u>						
Single pulse unclamped inductive switching 3/	3470	See 4.3.4, 116 devices, c = 0				
Electrical measurements		See table I, subgroup 2 herein.				
Safe operating area test	3474	$V_{DS} = 80$ percent of rated V_{DS} ; $V_{DS} \leq 200 \text{ V}$ maximum, $t_p = 10 \text{ ms}$ (see figure 6).				
Electrical measurements		See table I, subgroup 2 herein.				
<u>Subgroup 6</u>						
Not applicable						
<u>Subgroup 7</u>						
Gate charge	3471	Condition B				
<u>Test 1</u>						
On-state gate charge			$Q_{g(on)}$			nC
2N6804					29.0	
2N6806					31.0	
<u>Test 2</u>						
Gate to source charge			Q_{gs}			
2N6804					7.1	
2N6806					7.0	

See footnote at end of table.

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TABLE I. Group A inspection - Continued.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 7</u> – Continued						
<u>Test 3</u>						
Gate to drain charge			Q_{gd}			nC
2N6804					21.0	
2N6806					17.0	
Reverse recovery time	3473	$V_{DD} \leq -50 \text{ V}$	t_{rr}			ns
2N6804		$di/dt \leq -100 \text{ A}/\mu\text{s}; I_F = -11 \text{ A}$			250	
2N6806		$di/dt \leq -100 \text{ A}/\mu\text{s}; I_F = -6.5 \text{ A}$			400	

1/ For sampling plan, see MIL-PRF-19500.

2/ This test is required for the following end-point measurement only (not intended for screen 9, 11, or 13): JANS, table VIa of MIL-PRF-19500, group B, subgroups 3 and 4; JAN, JANTX, and JANTXV, table VIb of MIL-PRF-19500, group B, subgroups 2 and 3; and table VII of MIL-PRF-19500, group C, subgroup 6, and table IX of MIL-PRF-19500, group E, subgroup 1.

3/ This test is optional if performed as a 100 percent screen.

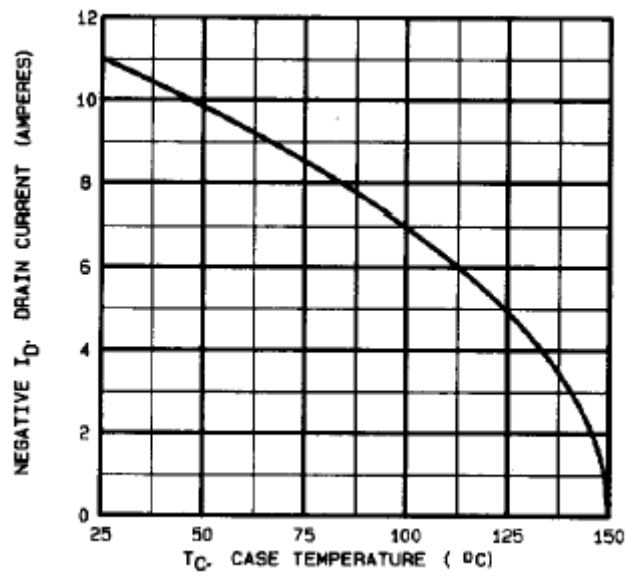
MIL-PRF-19500/562D

* TABLE II. Group E inspection (all quality levels) for qualification or re-qualification only.

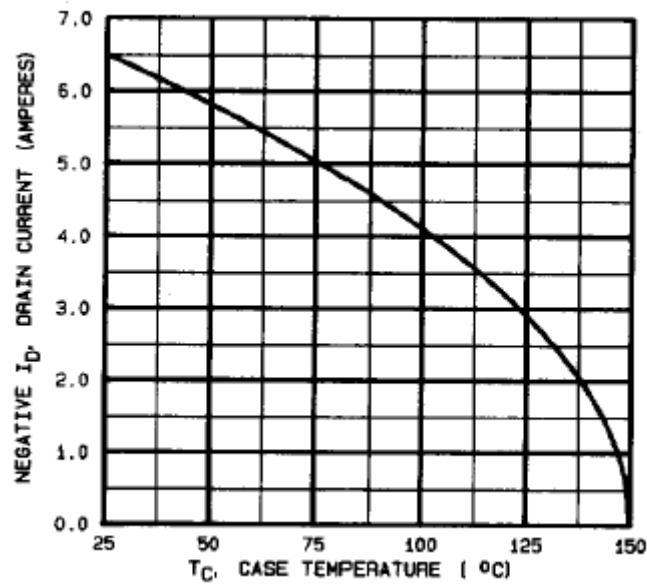
Inspection 1/	MIL-STD-750		Qualification inspection
	Method	Conditions	
<u>Subgroup 1</u>			12 devices c = 0
Temperature cycling	1051	Condition G, 500 cycles	
Hermetic seal	1071		
Fine leak Gross leak			
Electrical measurements		See table I, subgroup 2	
<u>Subgroup 2 2/</u>			45 devices c = 0
Steady-state reverse bias	1042	Condition A, 1,000 hours	
Electrical measurements		See table I, subgroup 2	
Steady-state gate bias	1042	Condition B, 1,000 hours	
Electrical measurements		See table I, subgroup 2	
<u>Subgroup 3</u>			3 devices, c = 0
DPA	2102		
<u>Subgroup 4</u>			sample size N/A
Thermal impedance curves		Each supplier shall submit their (typical) design thermal impedance curves. In addition, test conditions and $Z_{\theta JX}$ limit shall be provided to the qualifying activity in the qualification report	
<u>Subgroup 5</u>			
Not applicable			
<u>Subgroup 6</u>			3 devices
ESD	1020	Not required for devices classified as ESD class 1.	
<u>Subgroup 7</u>			22 devices c = 0
Commutating diode for safe operating area test procedure for measuring dv/dt during reverse recovery of power MOSFET transistors or insulated gate bipolar transistors	3476		

1/ JANHC and JANKC devices are qualified in accordance with MIL-PRF-19500.

2/ A separate sample may be pulled for each test.



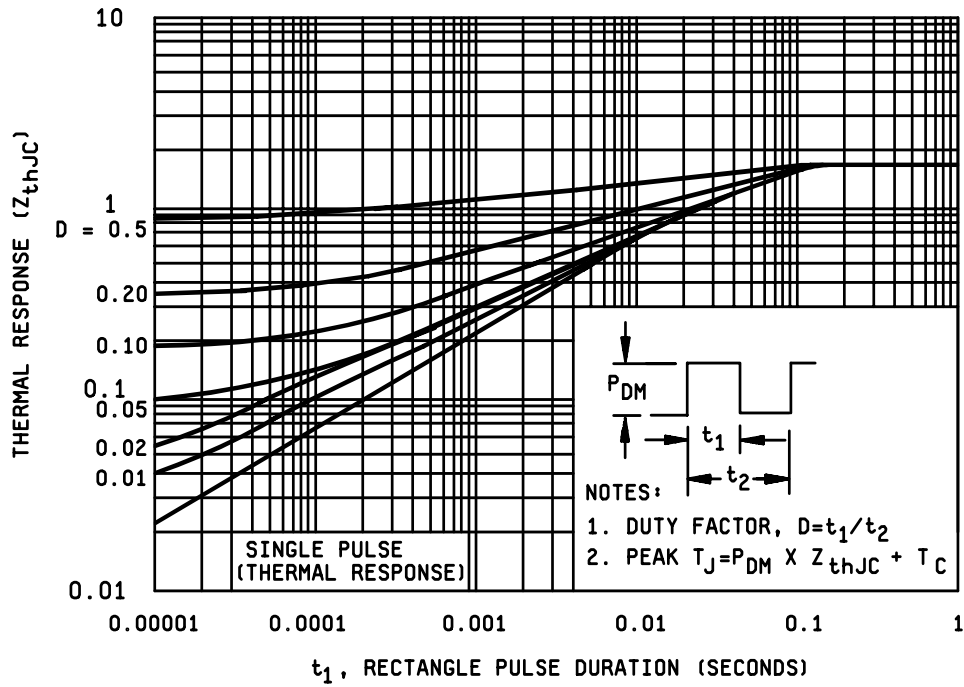
2N6804



2N6806

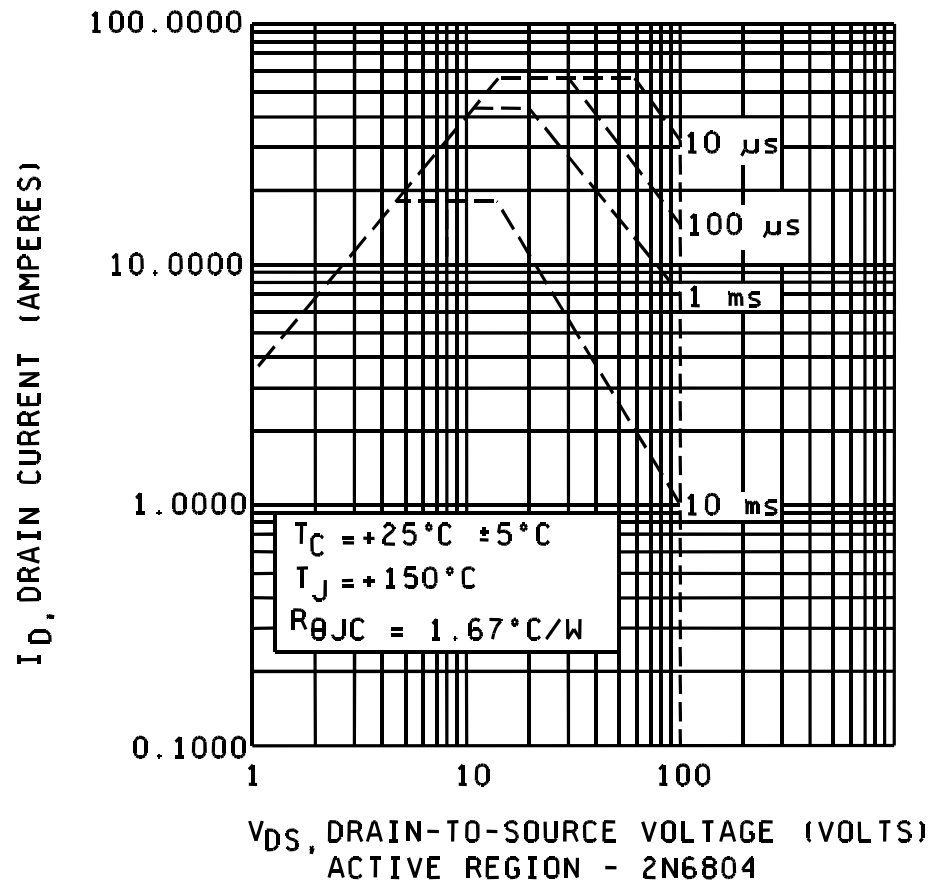
* FIGURE 4. Maximum drain current vs case temperature graphs.

2N6804 and 2N6806



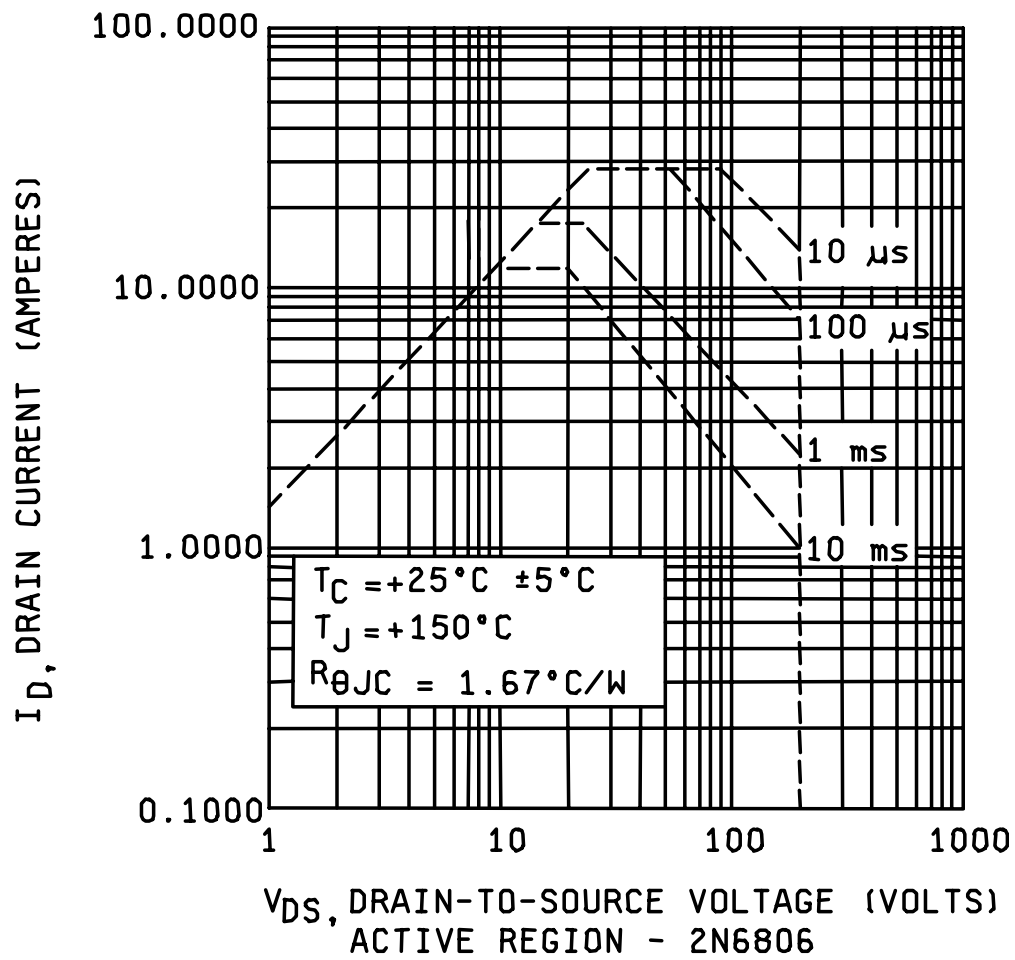
NOTE: These curves refer to devices packaged in a TO-204AA package only.

* FIGURE 5. Transient thermal impedance.



NOTE: These curves refer to devices packaged in a TO-204AA package only.

* FIGURE 6. Maximum safe operating area.



NOTE: These curves refer to devices packaged in a TO-204AA package only.

* FIGURE 6. Maximum safe operating area - Continued.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When actual packaging of material is to be performed by DoD personnel, these personnel need to contact the responsible packaging activity to ascertain requisite packaging requirements. Packaging requirements are maintained by the Inventory Control Points' packaging activity within the Military Department or Defense Agency, or within the Military Departments' System Command. Packaging data retrieval is available from the managing Military Departments' or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory.)

6.1 Notes. The notes specified in MIL-PRF-19500 are applicable to this specification.

* 6.2 Acquisition requirements. Acquisition documents must specify the following:

- a. Title, number, and date of this specification.
- b. Issue of DoDISS to be cited in the solicitation and if required, the specific issue of individual documents referenced (see 2.2.1).
- c. Packaging requirements (see 5.1).
- d. Lead finish (see 3.4.1).
- e. For die acquisition, the JANHC or JANKC letter version shall be specified (see figures 2 and 3).
- f. Type designation and quality assurance level.

* 6.3 Qualification. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers' List (QML) whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from Defense Supply Center, Columbus, ATTN: DSCC/VQE, P.O. Box 3990, Columbus, OH 43216-5000.

6.4 Cross-reference and complement list. Parts from this specification may be used to replace the following commercial Part or Identifying Number (PIN's). The term Part or Identifying Number (PIN) is equivalent to the term part number which was previously used in this specification.

Preferred types	Commercial types	Complement
2N6804	IRF9130, IRF9131, IRF9132, IRF9133	2N6756
2N6806	IRF9230, IRF9231, IRF9232, IRF9233	2N6758

6.5 Suppliers of JANHC and JANKC die. The qualified die suppliers with the applicable letter version (example JANHCA2N6804) will be identified on the QML.

* 6.6 Changes from previous issue. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:

Army - CR
Navy - EC
Air Force - 11
NASA - NA
DLA -CC

Preparing activity:

DLA - CC

(Project 5961- 2783)

Review activities:

Army - AR, MI
Navy - TD
Air Force - 19, 70

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2. The submitter of this form must complete blocks 4, 5, 6, and 7.
3. The preparing activity must provide a reply within 30 days from receipt of the form.

NOTE: This form may not be used to request copies of documents, nor to request waivers, or clarification of requirements on current contracts. Comments submitted on this form do not constitute or imply authorization to waive any portion of the referenced document(s) or to amend contractual requirements.

I RECOMMEND A CHANGE:**1. DOCUMENT NUMBER**

MIL-PRF-19500/562D

2. DOCUMENT DATE

5 November 2003

3. DOCUMENT TITLE SEMICONDUCTOR DEVICE, FIELD EFFECT TRANSISTOR, P-CHANNEL, SILICON TYPES 2N6804, 2N6806, JAN, JANTX, JANTXV, JANS, JANHC, AND JANKC

4. NATURE OF CHANGE (Identify paragraph number and include proposed rewrite, if possible. Attach extra sheets as needed.)

5. REASON FOR RECOMMENDATION**6. SUBMITTER**

a. NAME (Last, First, Middle initial)

b. ORGANIZATION

c. ADDRESS (Include Zip Code)

d. TELEPHONE (Include Area Code)
Commercial
DSN
FAX
EMAIL

7. DATE SUBMITTED
(YYMMDD)

8. PREPARING ACTIVITY

a. Point of contact: Alan Barone

b. TELEPHONE

Commercial DSN FAX EMAIL
614-692-0510 850-0510 614-692-6939 alan.barone@dla.mil

c. ADDRESS: Defense Supply Center
Columbus, ATTN: DSCC-VAC, 3990 East
Broad Street, Columbus, OH 43216-
5000

IF YOU DO NOT RECEIVE A REPLY WITHIN 45 DAYS, CONTACT:

Defense Standardization Program Office (DLSC-LM)
8725 John J. Kingman, Suite 2533, Fort Belvoir, VA 22060-6221
Telephone (703) 767-6888 DSN 427-68880